

AGENDA INEMI ROADMAP WEBINAR

The Americas Session

Tuesday, May 29, 2018

7:00 AM - 4:00 PM (Pacific/U.S.)

10:00 AM - 7:00 PM (Eastern/U.S.)

TIME (EDT/US)	TIME (PDT/US)	TECHNOLOGY WORKING GROUP (TWG)	PRESENTER(S)
10:00 AM	7:00 AM	Welcome/Overview	Grace O'Malley, Linda Wilson (iNEMI)
10:10 AM	7:10 AM	Environmentally Sustainable Electronics	Matthew Chalkley (IBM)
10:30 AM	7:30 AM	Modeling, Simulation & Design Tools	Lesley Polka (Intel)
10:50 AM	7:50 AM	MEMS & Sensors	Michael Gaitan (NIST)
11:10 AM	8:10 AM	Electronic Connectors	John MacWilliams (U.S. Competitors)
11:30 AM	8:30 AM	Interconnect PCB – Organic	Jack Fisher (HDPUG)
11:50 AM	8:50 AM	Passive Components	Ed Mikoski (ECIA)
12:10 PM	9:10 AM	Break	
12:30 PM	9:30 AM	Smart Manufacturing	Ranjan Chatterjee (Cimetrix)
12:50 PM	9:50 AM	Interconnect Substrates – Ceramic	Howard Imhof (SVMT-Silicon Valley Materials Technology)
1:10 PM	10:10 AM	Semiconductor Technology	Alan Allan (IRDS)
1:30 PM	10:30 AM	Board Assembly	Jasbir Bath (Bath Consultancy)
1:50 PM	10:50 AM	Mass Data Storage	Roger Hoyt (Hoyt Associates)
2:10 PM	11:10 AM	Flexible Hybrid Electronics	Jason Marsh (NextFlex)
2:30 PM	11:30 AM	Optoelectronics	Dick Otte (PROMEX Industries)
2:50 PM	11:50 AM	Break	
3:30 PM	12:30 PM	Packaging & Component Substrates	Bill Bottoms (3MTS-Third Millennium Test Solutions)
3:50 PM	12:50 PM	Thermal Management	Azmat Malik (Acuventures)
4:10 PM	1:10 PM	Test, Inspection & Measurement	To be determined (TBD)
4:30 PM	1:30 PM	RF Components & Subsystems	TBD
4:50 PM	1:50 PM	Energy Storage	TBD
5:10 PM	2:10 PM	Discussion/Break	
5:30 PM	2:30 PM	Final Assembly	TBD
5:50 PM	2:50 PM	Solid State Illumination	TBD
6:10 PM	3:10 PM	Power Electronics	TBD
6:30 PM	3:30 PM	Summary/Close	Grace O'Malley (iNEMI)
7:00 PM	4:00 PM	Adjourn	